

PATENT ASSIGNMENT

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SUBMISSION TYPE:		NEW ASSIGNMENT
NATURE OF CONVEYANCE:		ASSIGNMENT
CONVEYING PARTY DATA		
Name		Execution Date
Ken M. Lam		06/14/2006
RECEIVING PARTY DATA		
Name:	Atmel Corporation	
Street Address:	2325 Orchard Parkway	
City:	San Jose	
State/Country:	CALIFORNIA	
Postal Code:	95131	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	11456677	
CORRESPONDENCE DATA		
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NAME OF SUBMITTER:	Thomas Schneck	
Total Attachments: 4 source=Atm475#page1.tif source=Atm475#page2.tif source=Atm475#page3.tif source=Atm475#page4.tif		

OP \$40.00 11456677

A S S I G N M E N T

WHEREAS, the undersigned, KEN M. LAM, having an address of 4355 Kincaid Court, City of Colorado Springs, County of El Paso, State of Colorado 80906 (hereinafter termed Assignor) has invented certain new and useful improvements in an invention entitled: A METHOD TO PROVIDE SUBSTRATE-GROUND COUPLING FOR SEMICONDUCTOR INTEGRATED CIRCUIT DICE CONSTRUCTED FROM SOI AND RELATED MATERIALS IN STACKED-DIE PACKAGES; the undersigned Assignors hereby authorize and request that the serial number and filing date of said patent application be entered herein by the attorney in charge of the application, as soon as such information is known:

Serial No. 11/456,677
Filed: July 11, 2006

WHEREAS, ATMEL CORPORATION, a Delaware corporation, having an address of 2325 Orchard Parkway, San Jose, California 95131 (hereinafter termed Assignee) is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patent thereon when granted in the United States and foreign countries;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) and for other good and valuable consideration received by said Assignor from said Assignee, the receipt and sufficiency of which in full are hereby acknowledged by said Assignor:

1. Said Assignor does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor; and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any of said application specifically identified herein, and in and to each and every reissue or extension of said Letters Patent.

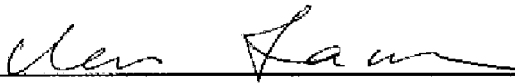
2. Said Assignor hereby covenants and agrees to cooperate with said Assignee whereby said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary

or desirable by Assignee to perfect in it the right, title and interest herein conveyed; (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of Letters Patent included herein, or for interference proceedings involving said invention and/or said improvements; (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor in lending such assistance and cooperation shall be paid by the Assignee.

3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives, and shall be binding upon said Assignor, his heirs, legal representatives and assigns.

4. Said Assignor hereby warrants and represents that he has not entered into any assignment, contract or understanding in conflict herewith.

IN WITNESS WHEREOF, this said Assignor has executed and delivered this instrument this 14th day of June, 2006.



KEN M. LAM